

ABSTRACT OF THE DISCLOSURE

A semiconductor device is used which is provided with a semiconductor chip having Au bumps on its surface and a chip-mounting substrate having external electrode lands on its chip-mounting face while having external electrode pads on its external connection face and constituted by bonding Au bumps on the semiconductor chip to internal electrode pads on the chip-mounting substrate while turning the semiconductor chip upside down, in which external electrode lands are arranged in areas corresponding to arrangement areas of internal electrode pads at the both sides of the chip-mounting substrate.